

PATENT APPLICATION

Attorney Docket: 54364

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gupta, et al.
Serial No.: 09/847,667
Filed: 5/1/01
For: Method for Bonding Wafers to Produce
Stacked Integrated Circuits
Group Art Unit: 2827

Examiner: James Mitchell

#4/a
9/16/02
JWM.

AMENDMENT

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

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TECHNOLOGY CENTER 2800

Sir:

In reply to the Office Action dated 3/13/02, in the above-identified patent application, Applicant submits the following Amendments and Remarks. Applicant respectfully requests that the following amendments be entered into the above-identified application and that the Examiner reconsider the grounds for rejection stated in the Office Action. The period for response to this office action has been extended by three months by the accompanying petition for extension of time.